

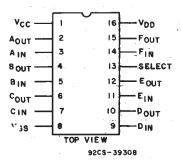
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Data sheet acquired from Harris Semiconductor SCHS069

CD4504B Types



TERMINAL ASSIGNMENT

CMOS Hex Voltage-Level Shifter for TTL-to-CMOS or CMOS-to-CMOS Operation

High-Voltage Types (20-Volt Rating)

Features:

- Independence of power-supply sequence considerations-V_{CC} can exceed V_{DD}; input signals can exceed both V_{CC} and V_{DD}
- Up and down level-shifting capability
- Shiftable input threshold for either CMOS or TTL compatibility
- Standardized symmetrical output characteristics
- 100% tested for quiescent current @ 20 V
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25° C
- 5 V, 10 V, and 15 V parametric ratings
- Meets all requirements of JEDEC Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

■ CD4504B hex voltage level-shifter consists of six circuits which shift input signals from the V_{CC} logic level to the V_{DD} logic level. To shift TTL signals to CMOS logic levels, the SELECT input is at the V_{CC} HIGH logic state. When the SELECT input is at a LOW logic state, each circuit translates signals from one CMOS level to another.

The CD4504B device is supplied in 16-lead ceramic dual-inline packages (D and F suffixes), 16-lead plastic dual-in-line packages (E suffix), 16-lead dual-in-line surface-mount plastic packages (M suffix), and in chip form (H suffix).

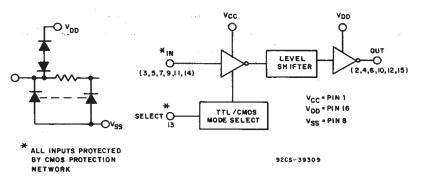


Fig. 1 - Functional diagram for CD4504B.

MAXIMUM RATINGS, Absolute—Maximum Values: DC SUPPLY-VOLTAGE RANGE, (VDD) Voltages referenced to VSS Terminal) -0.5V to +20V INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to VDD +0.5V DC INPUT CURRENT, ANY ONE INPUT ±10mA POWER DISSIPATION PER PACKAGE (PD): For TA = -55°C to +100°C 500mW For TA = +100°C to +125°C: Derate Linearity at 12mW/°C to 200mW DEVICE DISSIPATION PER OUTPUT TRANSISTOR FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW OPERATING-TEMPERATURE RANGE (TA) -55°C to +125°C STORAGE TEMPERATURE RANGE (Tstg): At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max +265°C

CD4504B Types

STATIC ELECTRICAL CHARACTERISTICS

	CONDITIONS				LIMITS AT INDICATED TEMPERATURES (°C)										
CHARACTERISTIC		Vo	VIN	VCC	VDD					+25			1		
		(V)	(V)	(V)	(V)	-55	-40	+85	+125	MIN	TYP	MAX	UNITS		
Quiescent Device Current, IDD Max and ICC in CMOS-CMOS Mode		-	0, 5	5	5	1	1	30	30	<u> </u>	0.02	1	μΑ		
		<u></u>	0,10	5	10	2	2	60	60	_	0.02	2			
			0, 15	5	-15	4	4	120	120	l –	0.02	4			
			0,20	5	20	20	20	600	600	_	0.04	20			
Quiescent Device Current, I _{CC} Max TTL-CMOS Mode			0, 5	5	5	5	5	6	6	_	2.5	5	mA		
			0, 10	5	10	5	5	6	6	_	2.5	5			
		_	0,15	5	15	5	5	6	6	_	2.5	5	1		
Output Low (Sink) Current, IOL Min		0.4	0.5	_	5	0.64	0.61	0.42	0.36	0.51	1	_			
		0.5	0,10	-	10	1.6	1.5	1.1	0.9	1.3	2.6	_			
		1.5	0, 15		15	4.2	4	2.8	2.4	3.4	6.8	_	1		
Output High (Source) Current, IOH Min		4.6	0,5	-	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	_	mA.		
		2.5	0,5	_	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	_			
		9.5	0, 10	_	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	_			
		13.5	0,15	—	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8				
Output Voltage: Low-Level, V _{OL} Max		[— <u>"</u>	0,5		5		0.0	05			0	0.05			
		-	0, 10	_	10	0.05			_	0	0.05	1 1			
		_	0,15	_	15		0.0	05			0	0.05	7		
Output Voltag	-	_	0,5	_	5	4.95 4.9		4.95	5	_	1				
High-Level, V _{OH} Min		_	0,10		10	9.95		9.95	10	_	1				
		_	0, 15	_	15	14.95		14.95	15	_					
Input Low	TTL-CMOS	1		5	10	0.8 0.8 1.5			_	_	0.8	v			
Voltage, V _{II} Max	TTL-CMOS	1	_	5	15				_		8.0				
Note 1	CMOS-CMOS	1	_	5	10						1.5				
	CMOS-CMOS	1.5	_	5	15				_		1.5				
	CMOS-CMOS	1.5	_	10	15		3			_	3				
Input High Voltage, V _{IH} Min Note 1	TTL-CMOS	9	_	5	10		2	!		2		_	1		
	TTL-CMOS	13.5	_	5	15	2 3.5 3.5 7			2		_				
	CMOS-CMOS	9		5	10				3.5		_				
	CMOS-CMOS	13.5	_	5	15				3.5		_				
	CMOS-CMOS	13.5	_	10	15				7	_	_				
Input Current, I _{IN} Max		_	0,18	_	18	±0.1	±0.1	±1	±1		±10 ⁻⁵	±0.1	μА		

Note 1: Applies to the 6 input signals. For mode control (P13), only the CMOS-CMOS ratings apply.

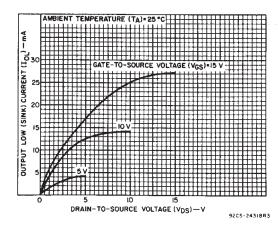


Fig. 2 - Typical output low (sink) current characteristics.

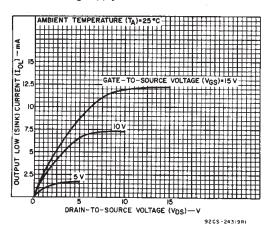
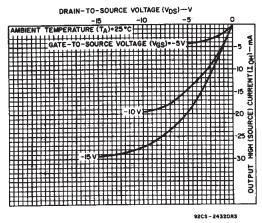


Fig. 3 - Minimum output low (sink) current characteristics.

CD4504B Types



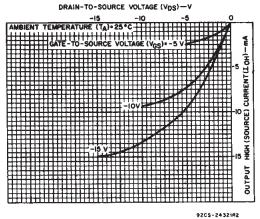


Fig. 4 - Typical output high (source) current characteristics.

Fig. 5 - Minimum output high (source) current characteristics.

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	VDD	LIM	UNITS	
OHARAOTERISTIO	(V)	Min.	Max.	ONITS
Supply-Voltage Range (For T _A = Full Package-Temperature Range)		3	18	٧

DYNAMIC ELECTRICAL CHARACTERISTICS, At TA = 25°C; Input tr,tf = 20 ns, CL = 50 pF, RL = 200 Ω

CHARACTERISTIC		SHIETING MODE	VCC 00	VDD (V)	LIMITS		
CHARACTERISTI		SHIFTING MODE	VCC (V)	(א) טטא	TYP.	MAX.	UNITS
		TTL to CMOS	5	10	140	280	
		$V_{DD} > V_{CC}$	5	15	140	280	
Propagation Delay:	Ĩ	CMOS to CMOS	5	10	120	240	
High-to Low,	t _{PHL}	$V_{DD} > V_{CC}$	5	15	120	240	1
		. *	10	15	70	140	
	Ì	CMOS to CMOS	10	5	275	550	1
		$V_{CC} > V_{DD}$	15	5	275	550	
			15	10	70	140	
Low-to-High,		TTL to CMOS	5	10	140	280	ns
	}	$V_{DD} > V_{CC}$	5	15	140	280	
		CMOS to CMOS	5	10	120	240	1
	telH	$V_{DD} > V_{CC}$	5	15	120	240	
			10	15	70	140	
		CMOS to CMOS	10	5	200	400	1
	200	V _{CC} > V _{DD}	15	5	200	400	
	E serv		15	10	60	120	
			4	5	100	200	1
Transition Time,	t _{THL} ,t _{TLH}	All Modes		10	50	100	
				15	40	80	
Input Capacitance, Cin		Any Input			5	7.5	pF

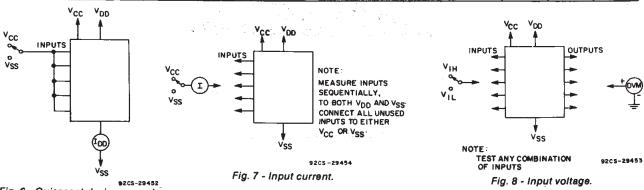


Fig. 6 - Quiescent device current.

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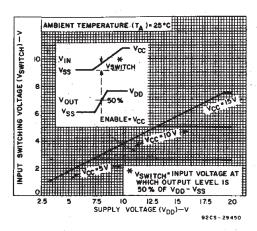


Fig. 9 - Typical input switching as a function of high-level supply voltage. (SELECT at V_{CC}-CMOS mode).

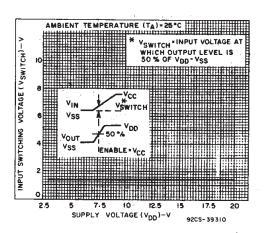


Fig. 10 - Typical input switching as a function of high-level supply voltage (SELECT at Vss-TTL mode).

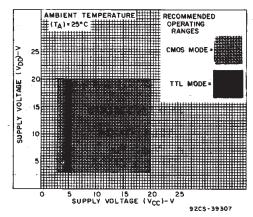
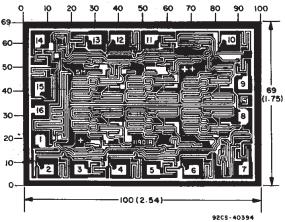


Fig. 11 - High-level supply voltage vs. low-level supply voltage.



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch) .

Dimensions and pad layout for CD4504BH.

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